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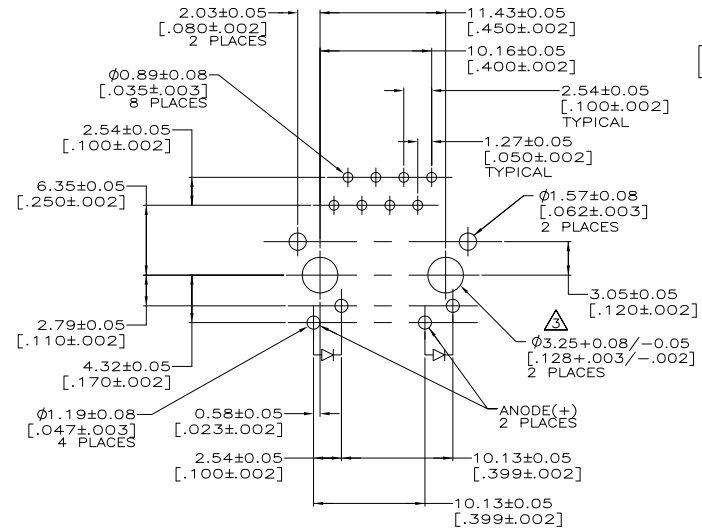
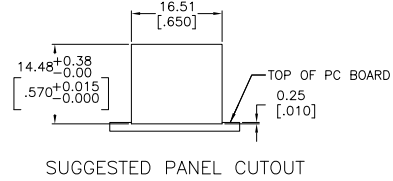
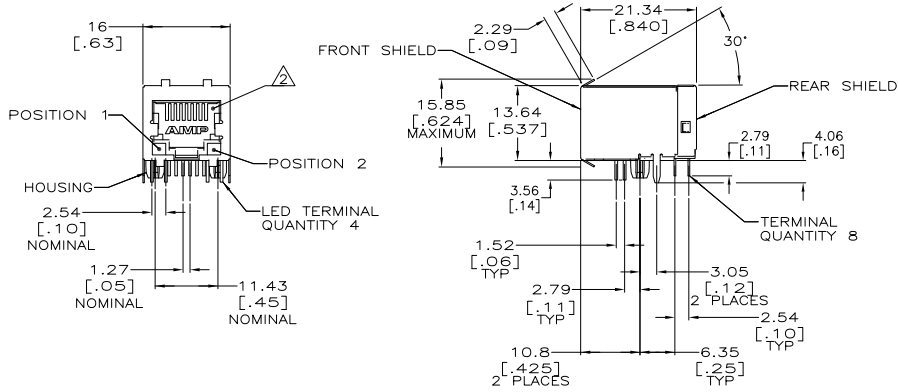
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LOC	DIST	REVISIONS					
AA	00	F	LNK	DESCRIPTION	DATE	BY	APPD
		E2		REVISED PER ECO-11-005033	26MAR11	RLK	HMR



- MATERIAL: HOUSING - PBT THERMOPLASTIC BLACK, UL94V-0.
TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27µm[.000050] MINIMUM NICKEL AND 2.03 µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.

LED COLOR	POSITION 1	POSITION 2	PART NUMBER
YELLOW	GREEN	GREEN	5569564-5
GREEN	GREEN	GREEN	5569564-4
GREEN	YELLOW	YELLOW	5569564-1

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DWG	L. VARELA - 07JAN2005	CHK	S. WESTMAN - 07JAN2005	APPD	S. WESTMAN - 07JAN2005
TE Connectivity					
DIMENSIONS: mm [INCHES]					
TOLERANCES UNLESS OTHERWISE SPECIFIED:					
0 PLG	± .005	1 PLG	± .005	2 PLG	± .005
3 PLG	± .005	4 PLG	± .005	ANGLES	± .005
MATERIAL FINISH					
APPLICATION SPEC: 108-1163			SIZE CASE CODE DRAWING NO: 114-2154		
CUSTOMER DRAWING			SCALE: 2:1 SHEET 1 of 1 REV E2		